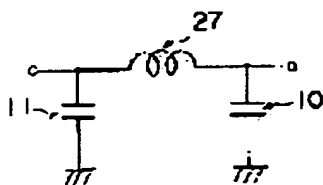


D-077



(57)Abstract:

**PURPOSE:** To obtain a pie filter where packaging density is improved by arranging a chip capacitor incorporating plural capacitor elements on one side of a part interposed with a circuit board and arranging a ferrite chip based on the other side.

**CONSTITUTION:** Between two capacitor elements 10 and 11 incorporated in a chip capacitor 100, the inductor element 27 incorporated in a ferrite chip base 200 is arranged, and a pie filter circuit is formed as a whole. Thus, the ferrite chip bead 200 and the chip capacitor 100 are arranged at the correspondent location of the front and back surfaces of the circuit board and are connected to each other through holes 34a and 34b. As a result, the packaging space is saved by one capacitor as compared with a case where three elements of two capacitors and one ferrite based are arranged on the circuit board, the front and back surfaces of the circuit board are used so that a pie shape filter which is formed in a compact shape can be obtained.

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(72)Inventor : UCHIDA AKIRA

(54) PI TYPE FILTER